

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

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10997 U.S. PTO
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In re the Application of:

Hui et al.

Serial No: TBD

Filed: 10/18/01

For: DIE PAD FOR INTEGRATED CIRCUITS

Docket No.: TI-27874

Examiner: TBD

Art Unit: TBD

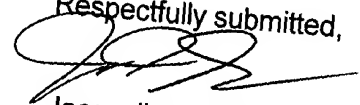
INFORMATION DISCLOSURE STATEMENT

Assistant Commissioner for Patents
Washington, DC 20231

Dear Sir:

Please make the references listed on the enclosed PTO-1449 of record under 37 C.F.R. 1.56, 1.97, and 1.98 in the patent application identified above. A copy of the listed references are enclosed.

Respectfully submitted,



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